MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

IBGA80 10x10
CASE 503BT
ISSUE 0

DATE 26 JUL 2017

NOTES:
2. CONTROLLING DIMENSION MILLIMETERS
3. DIMENSION A IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE 0.5°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=196.66 MICRONS, Y=150.33 MICRONS & Z75 MICRONS.

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